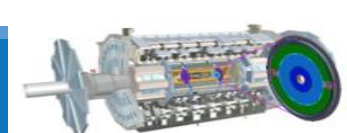


Maxime Morenas/OMEGA on behalf of ATLAS HGTD

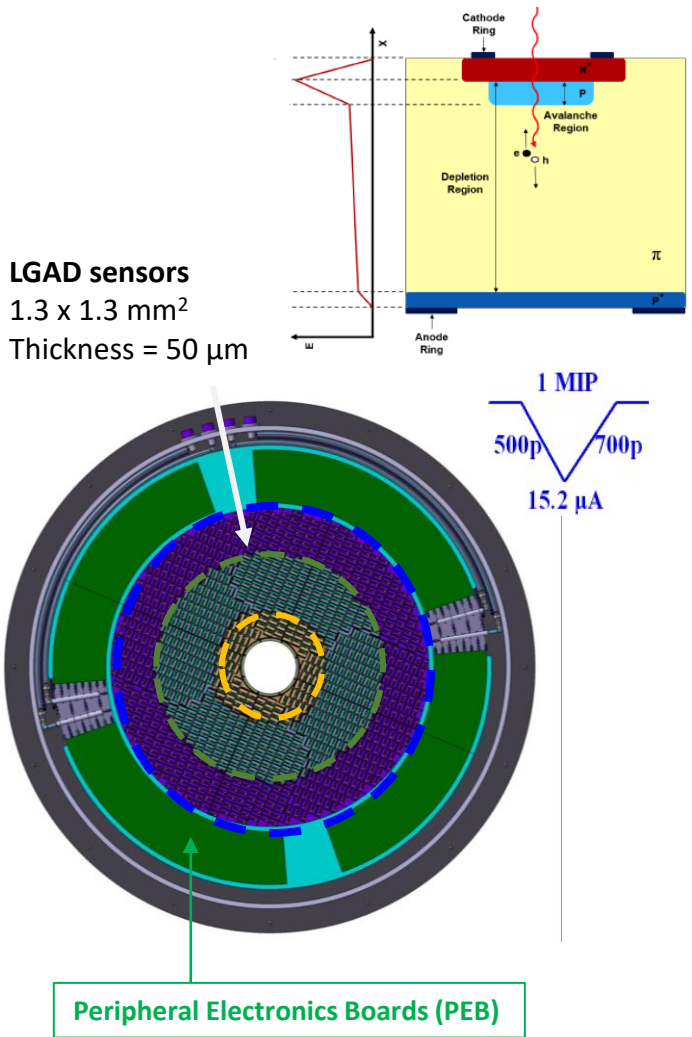
IEEE NSS, 5 October 2020

ALTIROC1

A 25 pico-second time resolution ASIC for the ATLAS
High Granularity Timing Detector (HGTD)



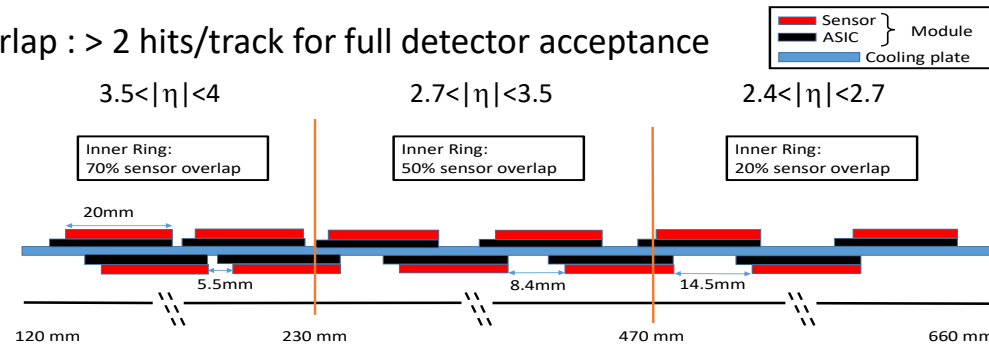
High Granularity Timing Detector in HL-LHC



REQUIREMENTS of the HGTD DETECTOR

- **Luminosity measurement**: sum of the hits for each Bunch Crossing
- **Time measurement** for minimum ionizing particle with a resolution between **25 ps to 50 ps per track** over the detector's lifetime
35 ps to 70 ps per hit

Overlap : > 2 hits/track for full detector acceptance

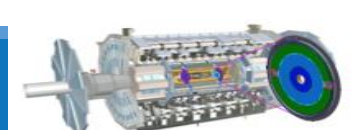


Active area: LGAD sensor bump-bonded onto 2 ASICs (225 channels/ASIC)

- **Inner ring** : 12 cm < R < 23 cm (3.5 < η < 4.0) replaced each 1000 fb⁻¹
- **Middle ring** : 23 cm < R < 47 cm (2.7 < η < 3.5) replaced at 2000 fb⁻¹
- **Outer ring** : 47 cm < R < 64 cm (2.4 < η < 2.7) never replaced

Rings replacement allows to keep:

- 2.5x10¹⁵ n_{eq}/cm² max (w/SF=1.5) and TID 2 MGy max (w/SF=2.25)
- Charge in irradiated sensor > 4fC



Requirements for the ASIC

Maximum jitter (σ_{elec})	25 ps at 10 fC at the start of the HL-LHC and 70 ps for 4 fC at the end
TDC contribution	< 10 ps
Time walk contribution	< 10 ps
Clock contribution	< 15 ps

TDC conversion time	< 25 ns
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PAD size	1.3 x 1.3 mm ² x 50 μ m => Cdet = 4 pF
ASIC size and channels /ASIC	2x2 cm ² 15x15=225 channels/ASIC
Single PAD noise (ENC)	< 3000 e- or 0.5 fC
Minimum threshold	2 fC
Dynamic range	4 fC to 50 fC

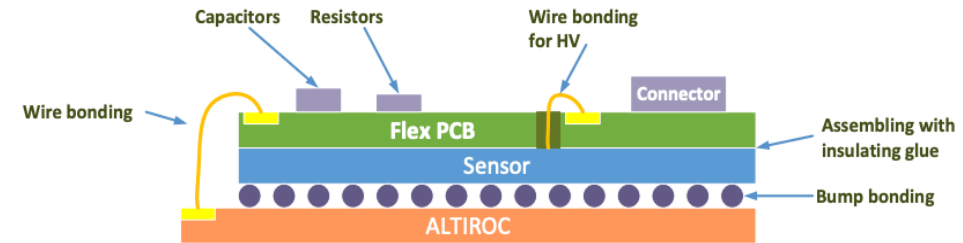
TID Tolerance	2 MGy (inner modules replaced after each 1000 fb ⁻¹ , middle ring after 2000 fb ⁻¹)
Full chip SEU probability	< 5 % / hour

Voltage and Power dissipation per ASIC	1.2V and 300 mW cm ⁻² => 1.2 W/ASIC (225 ch) or 4.4 mW/channel and 200 mW for the common part
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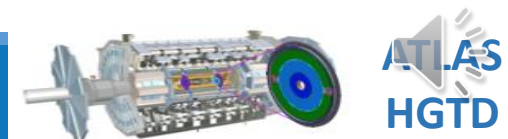
Main contributors to time resolution

$$\sigma_{hit}^2 = \sigma_{Landau}^2 + \sigma_{clock}^2 + \sigma_{elec}^2$$

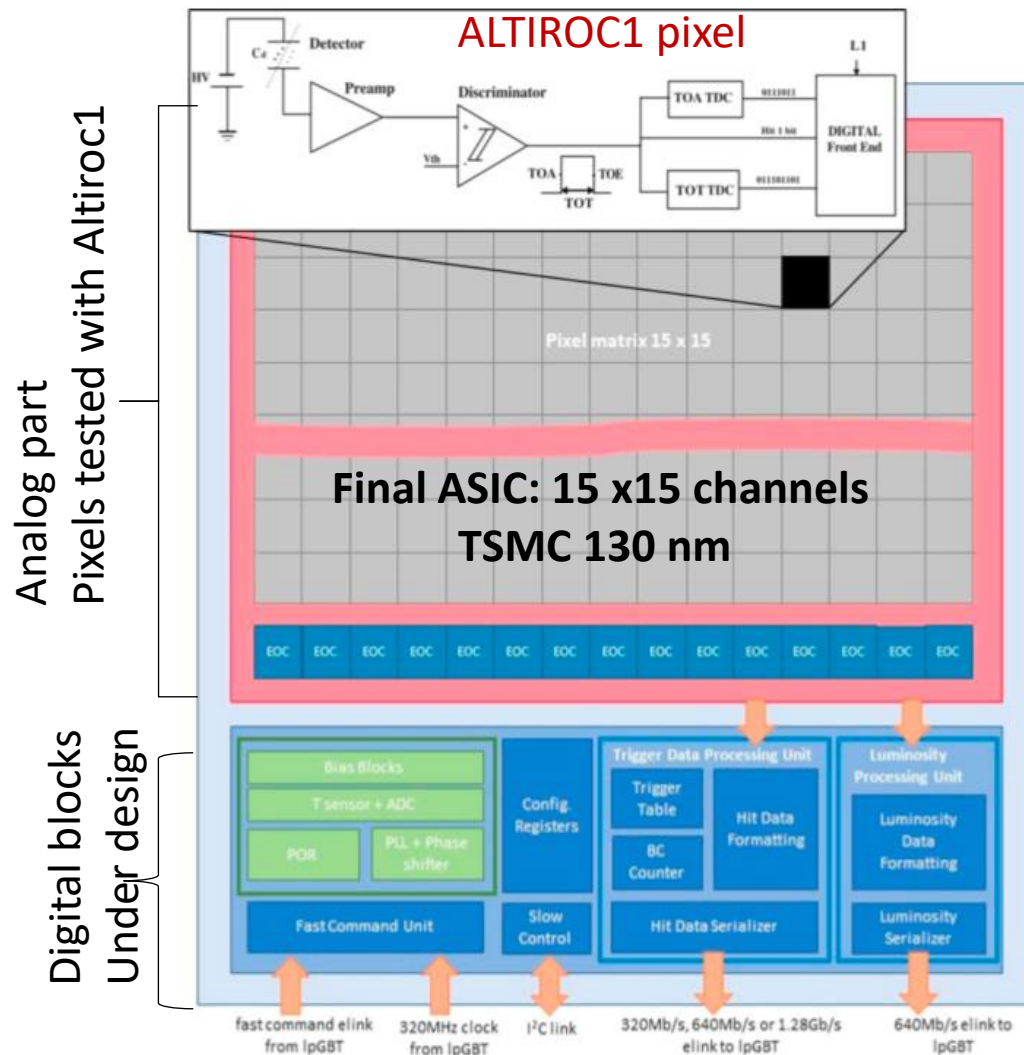
with $\sigma_{elec}^2 = \sigma_{Time\ walk}^2 + \sigma_{jitter}^2 + \sigma_{TDC}^2$



ASIC designed in CMOS 130 nm



Front end electronics-ASIC: ALTIROC, analog part

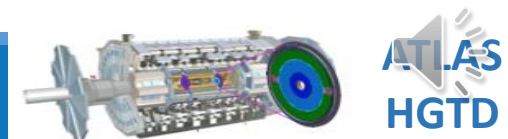


- Main challenge = small jitter (low noise/capacitance) down to 4 fC
 ⇒ **Analog FE performance crucial**

$$\sigma_{jitter} = \frac{N}{dV/dt} = \frac{e_n C_d}{Q_{in}} \sqrt{t_d}$$

C_d : sensor cap (~4 pF)
 t_d : LGAD drift time, 600 ps
 Q_{in} : MIP charge (10 fC at start, 4 fC at end)
 e_n : noise spectral density of input trans.

- ⇒ **ALTIROC1 prototypes** (5x5 ch), which integrate
- A voltage **preamplifier** followed by a **discriminator**:
 - Time walk correction made with a Time over Threshold (TOT) architecture
- **Two TDC** (Time to Digital Converter) to provide digital **Hit data** =Time of Arrival (TOA) + Time Over Threshold (TOT) measurement
 - TOA TDC: bin of 20 ps (7 bits), range of 2.5 ns, to be centered on the bunch crossing
 - TOT TDC: bin of 160 ps (9 bits), range of 20 ns
- One local memory (**SRAM**):
 - 17 bits of the time measurement (Hit data) stored until L0/L1 trigger (~ 1 MHz) if hit detected (otherwise 1 bit stored), trigger latency = 10 μ s in Altiroc1, will be 35 μ s in full size ASIC (Altiroc2)
- **Phase shifter**

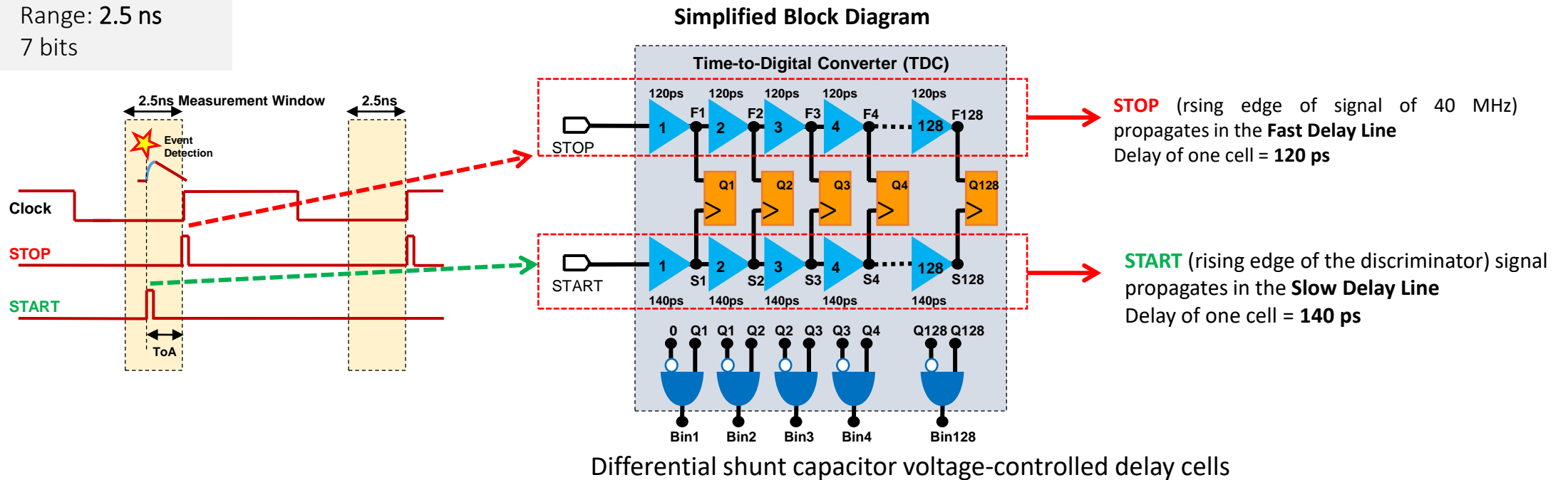


TOA TDC Architecture : Vernier Delay Line

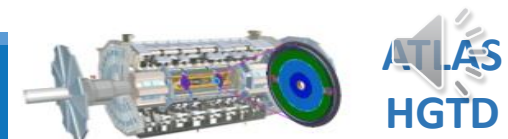
TOA TDC

- Resolution: 20 ps
- Range: 2.5 ns
- 7 bits

TDC Power consumption $0.4 \text{ mA} * 1.2 \text{ V} = 0,5 \text{ mW @ 10\% occupancy}$

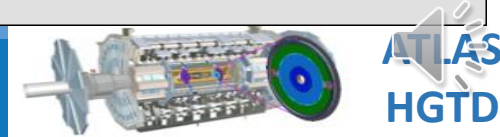
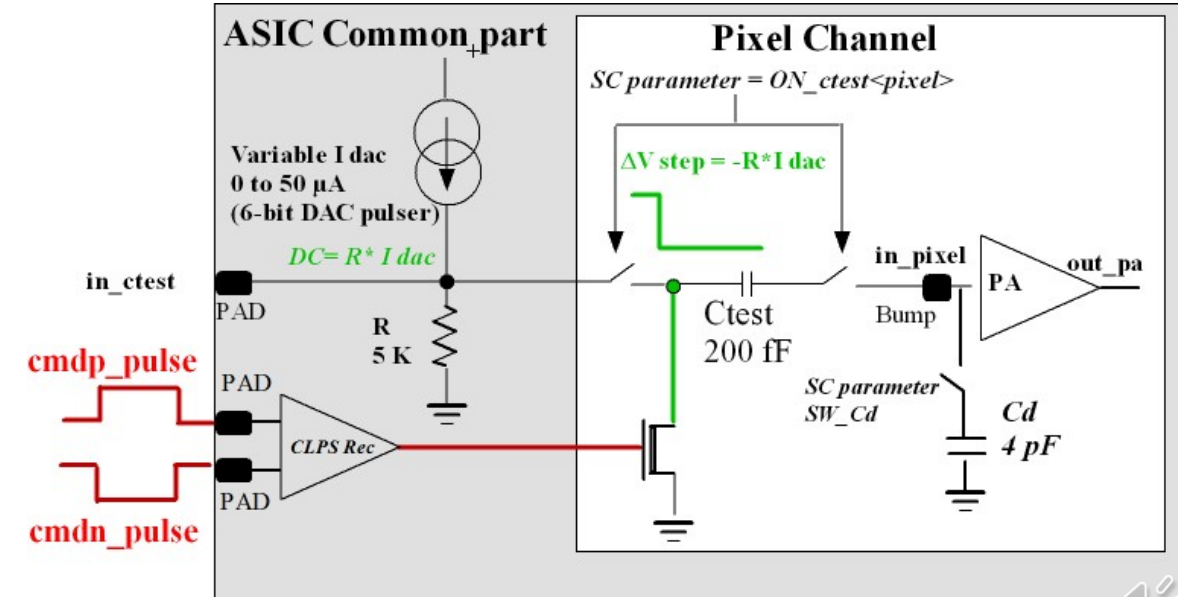
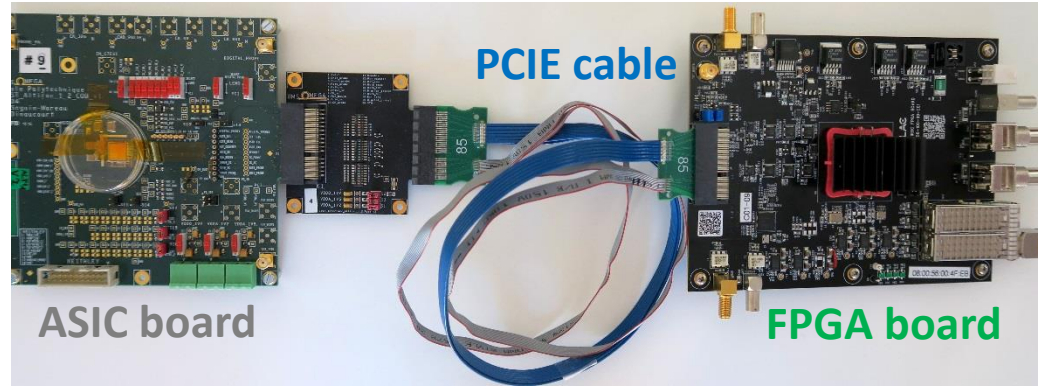
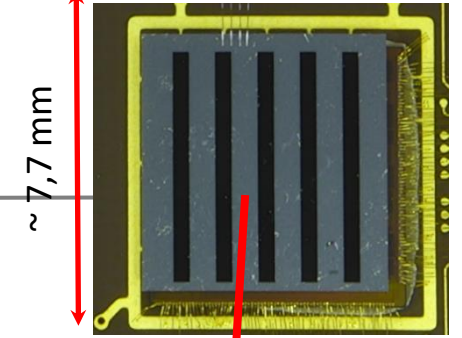


- **START** pulse comes first and initializes the TDC operation. **STOP** pulse follows the **START** with a delay that represents the time interval to be digitalized.
- At each tap of the Delay Line, **STOP** signal catches up to the **START** signal by the difference of the propagation delays of cells in Slow and Fast branches: i.e. $140\text{ps} - 120\text{ps} = 20\text{ps}$ (LSB).
- The number of cells necessary for **STOP** signal to surpass the **START** signal represents the result of TDC conversion
- Cycling configuration used in order to reduce the total number of Delay Cells.
- TDC range is equal to $128 * 20 \text{ ps} = 2.56 \text{ ns}$



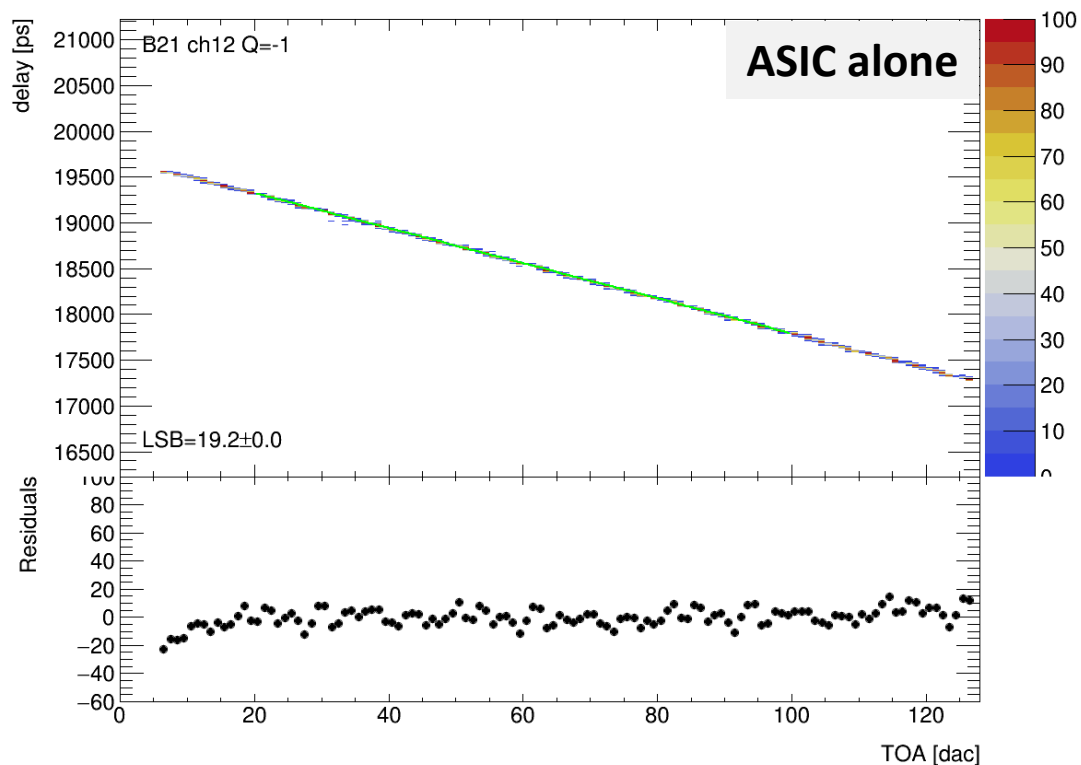
TESTBENCH

- **ALTIROC1** : testbench measurements (ASIC alone or with sensor), irradiation tests, testbeam
- **Setup**: ASIC board (ASIC alone or bump bonded onto sensor) + FPGA board
 - Charge injection (0 up to 50 fC) using **ASIC internal calibration pulser** controlled by **cmd_pulse** input, generated by the FPGA, synchronous to 40 MHz clock
 - ASIC alone: Cd=4 pF can be set by SC to mimic sensor capacitor
 - **External trigger**, width and delay tunable by 10 ps steps : used to characterize the TOA and TOT TDC alone

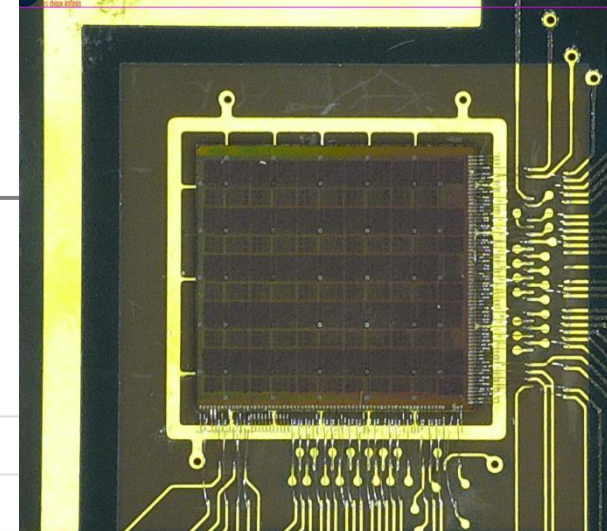
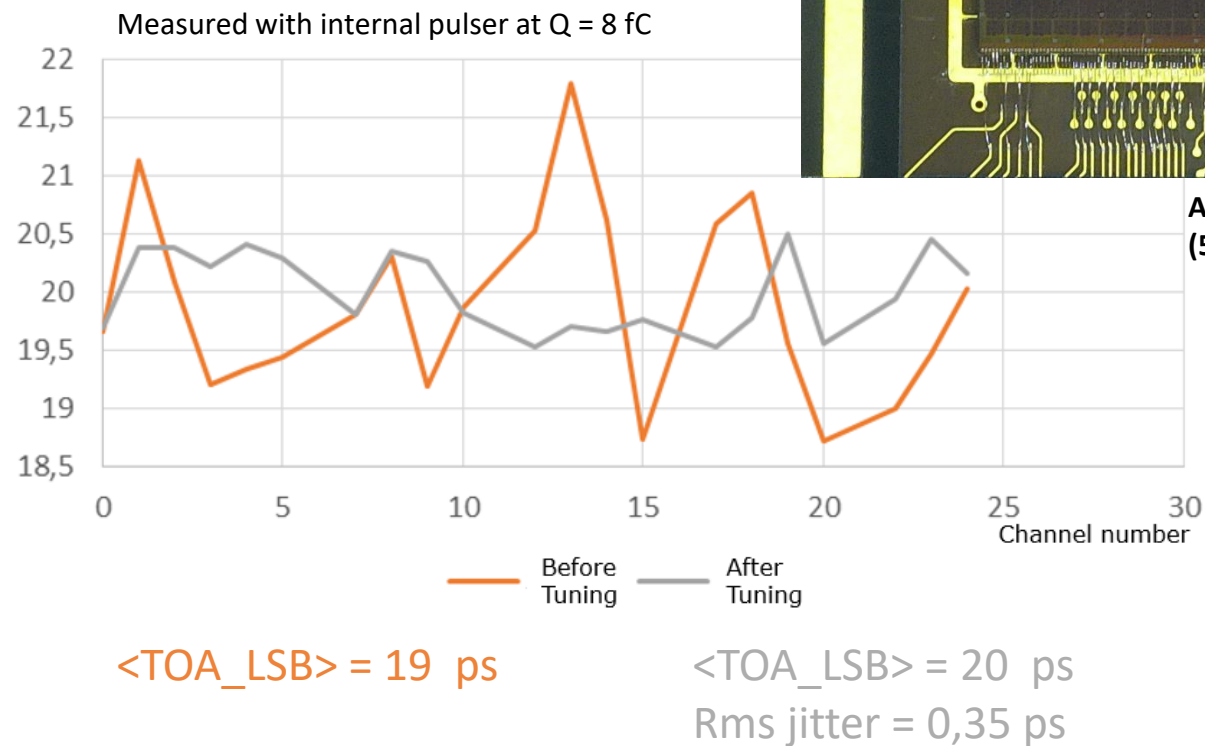


ALTIROC1 – TOA TDC performance

Delay versus $\langle \text{TOA} \rangle$

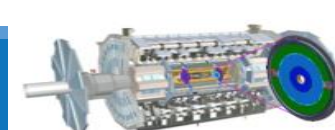


$\langle \text{TOA LSB} \rangle$ vs channel



ALTIROC1
(5 × 5 channels)

- TOA_LSB and TOT_LSB can be adjusted to 20 ps and 160 ps per channel using Slow Control parameters



ALTIROC1 - DLL performance in temperature

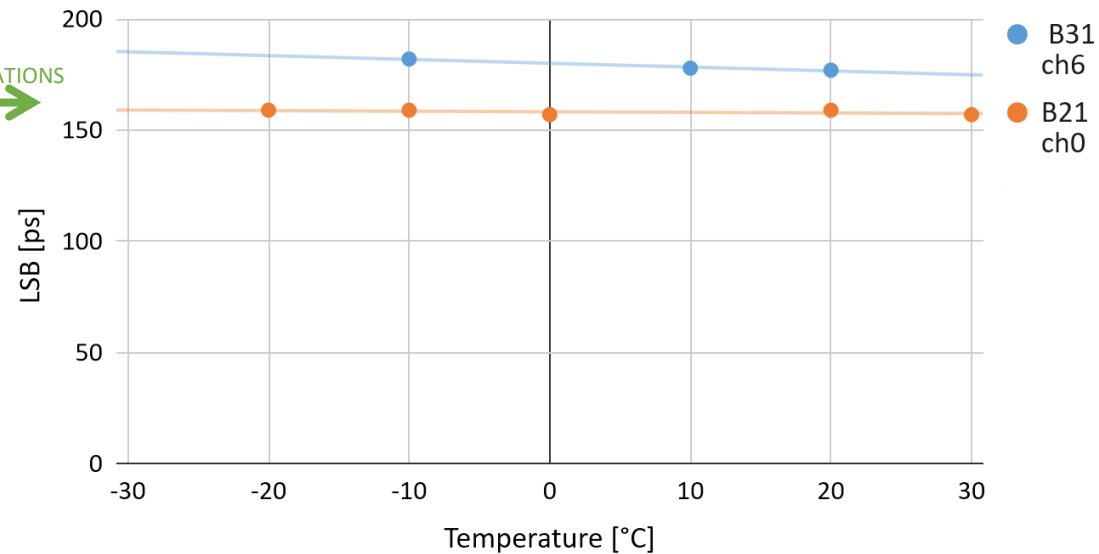
3 DLL : **Fast** (120 ps), **Slow** (140 ps), **Coarse** (160 ps)

TDC for TOA
Achieving 20 ps LSB

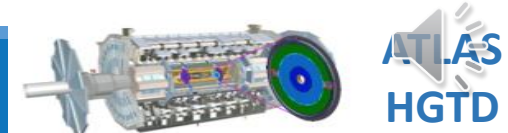
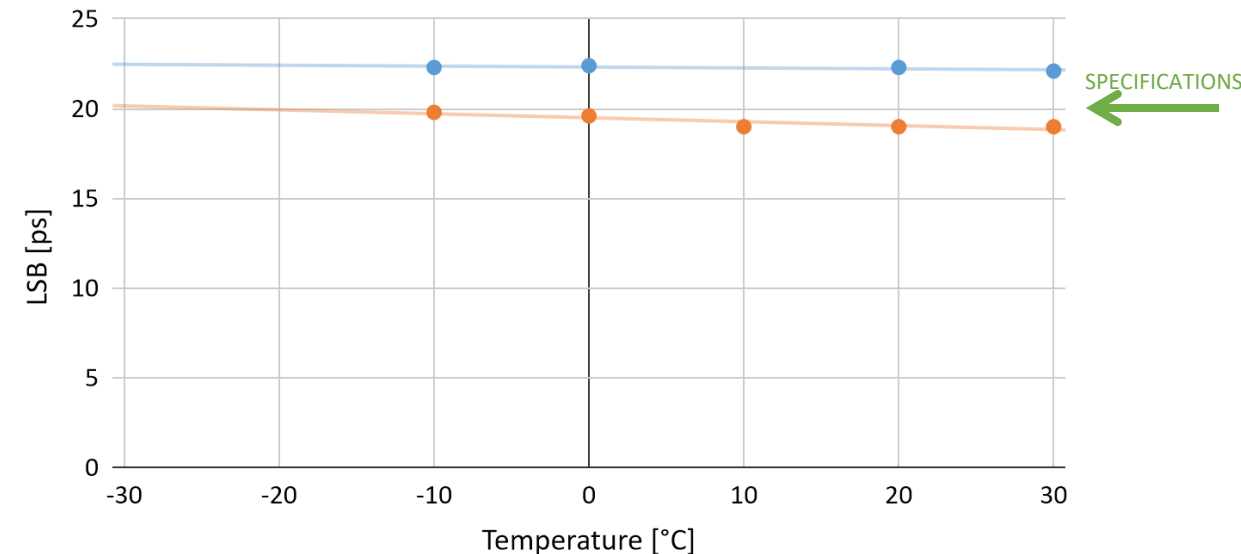
TDC for TOT
Achieving 160 ps LSB

- Different <LSB> because not tuned
- Average **temperature variability** : below 3%

TOT LSB

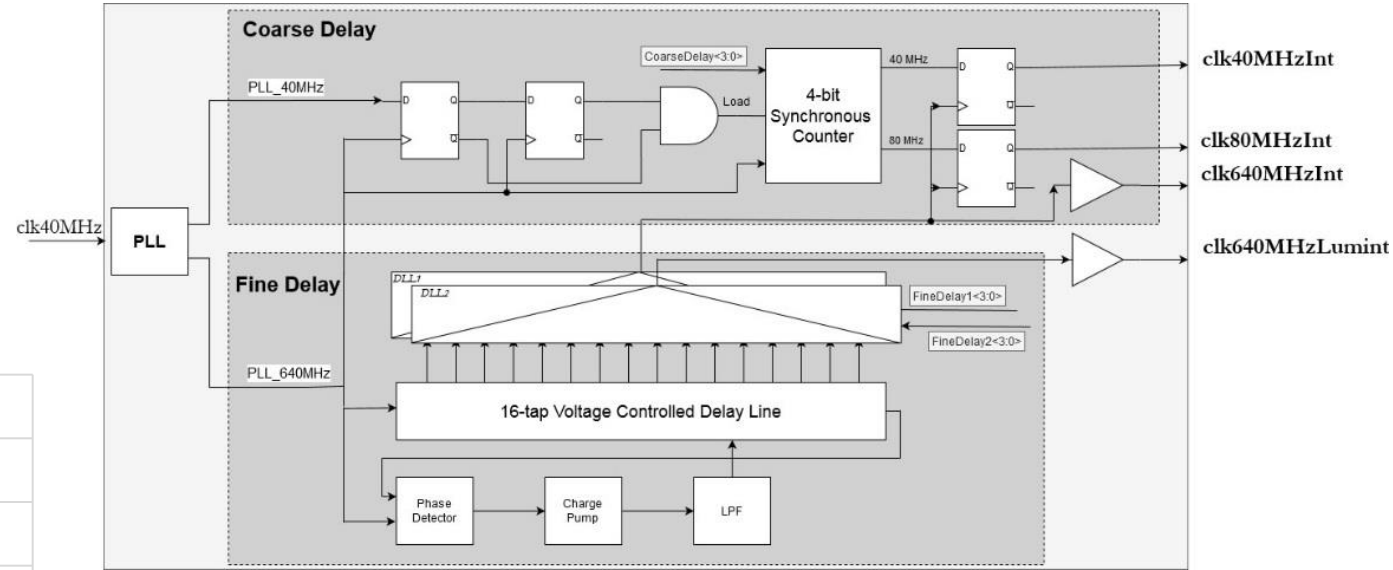
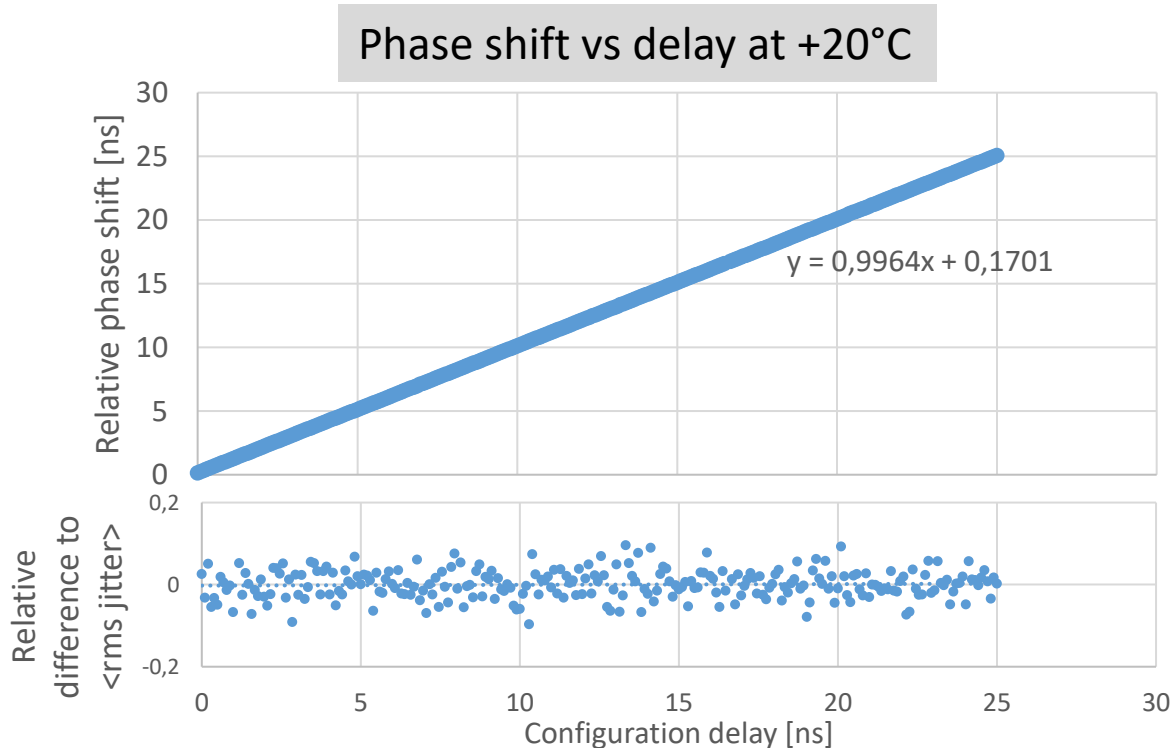


TOA LSB

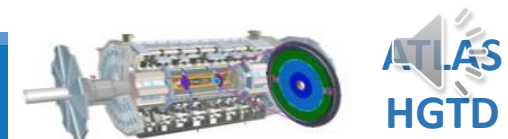


ALTIROC1 – Phase shifter performance

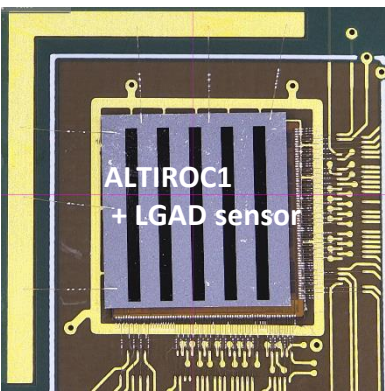
- Used to center the 2.5 ns measurement time window of the TOA TDC on the Bunch Crossing
- Requirements:
 - Step 100 ps ± 10 ps, range 25 ns**
 - Power dissipation < 10 mW



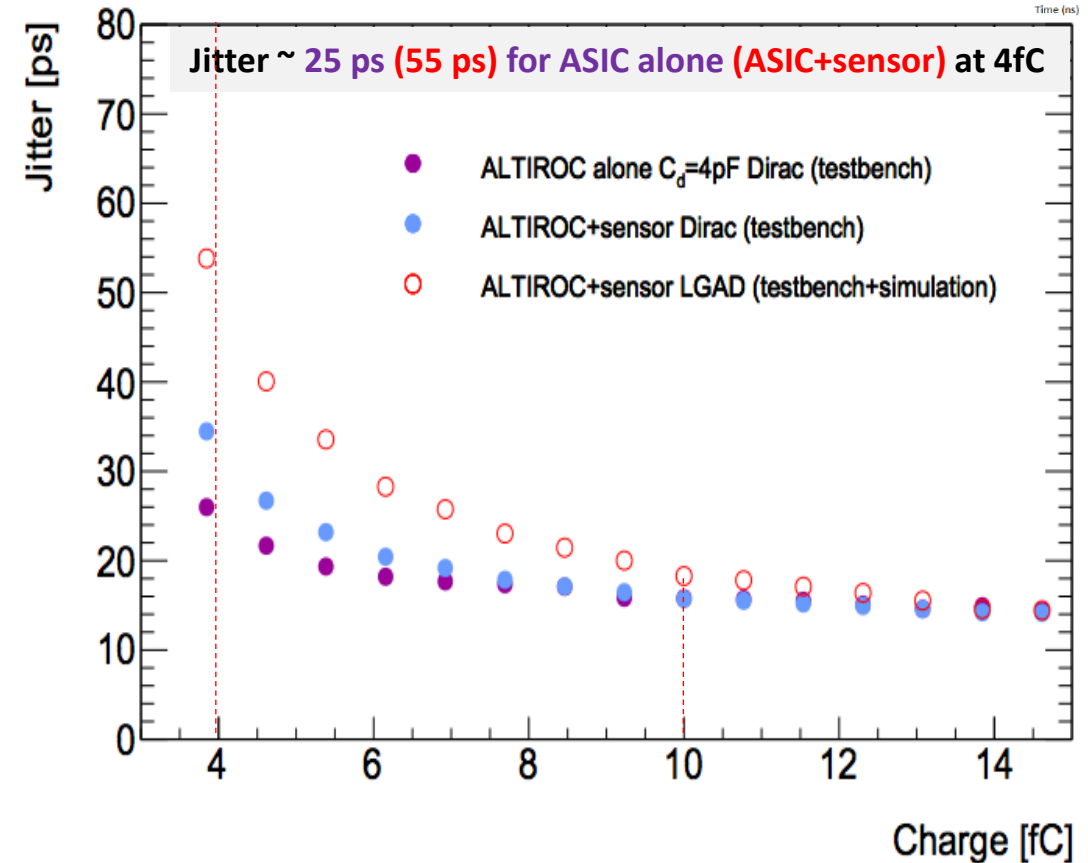
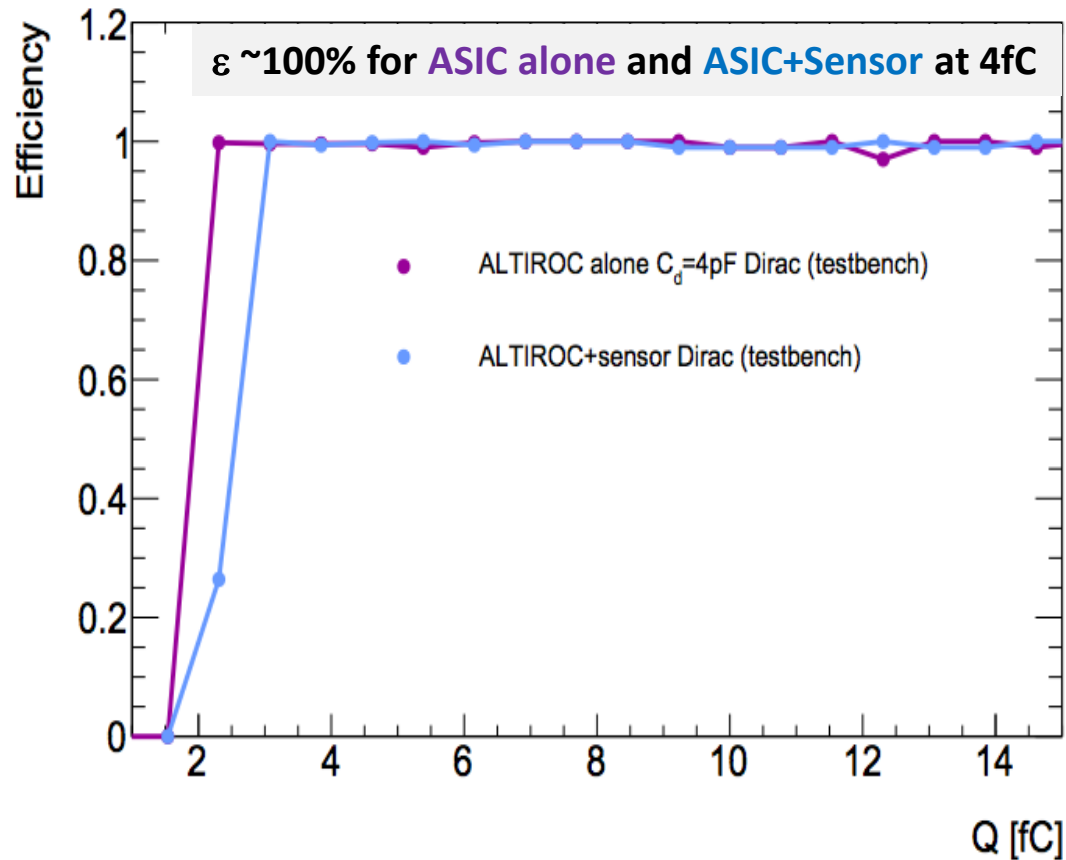
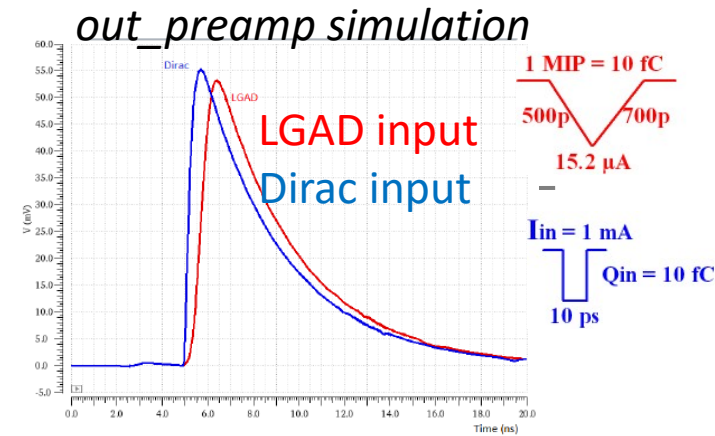
- Results :
 - Shift the 40 MHz clock by steps of **98 ps** LSB and range achieved
 - <output clock rms jitter>**_{temperature,range} : **14 ps**



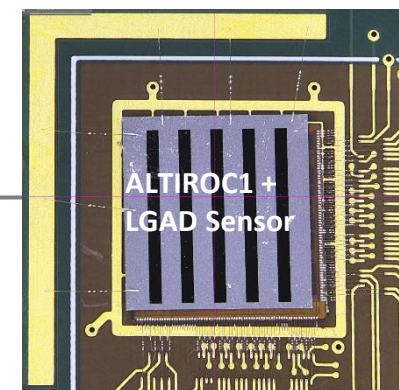
ALTIROC1 - Analog performance at system level



System level = ASIC bump-bonded onto a 5x5 LGAD sensor (1.3 mm x 1.3 mm x 50 μm)

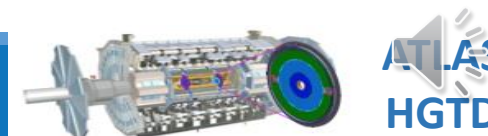
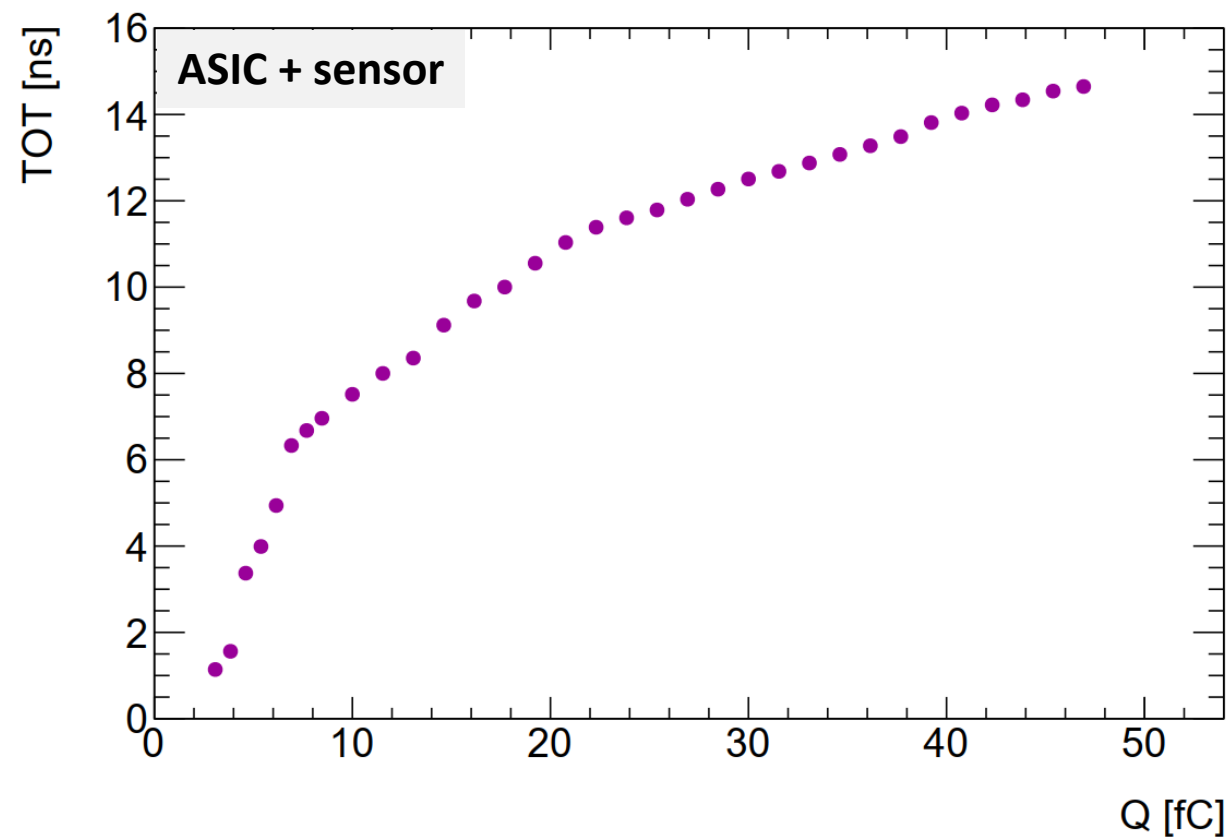
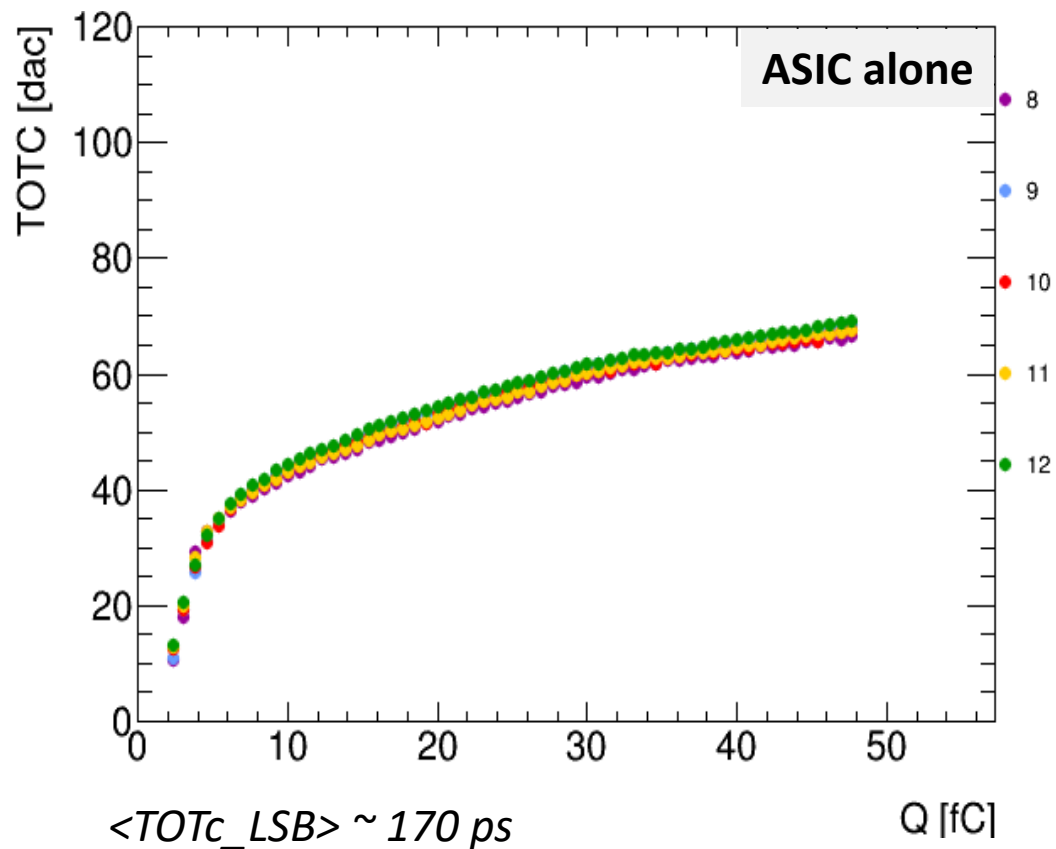


ALTIROC1 - Analog performance at system level



TOTc of Ch4, Cd = 4 pF vs Qinj for several boards

TOTc vs Qinj



SUMMARY & CONCLUSIONS

- Good analog performance demonstrated with ALTIROC1 prototypes
 - Very useful to understand system issues with sensor
 - Jitter (ASIC+sensor) < 35 ps at 4 fC with calibration pulse
 - Vth (ASIC+sensor) can be set at 2 fC
 - More results about under irradiation tests and testbeam presented by **Dr. Yusheng Wu (2 nov.)**
- Design of first full size ASIC (ALTIROC2) is on going, submission end 2020
 - Mix of Digital On Top (DOT) and Analog On Top (AOT), compromise between power dissipation, timing verifications, analog performance
 - Analog performance crucial , floor plan (power distribution, grounding) done AoT
 - Tests at system level will be done



BACK UP : TOA calibration

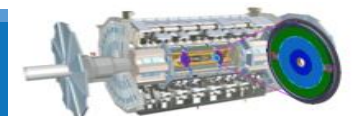
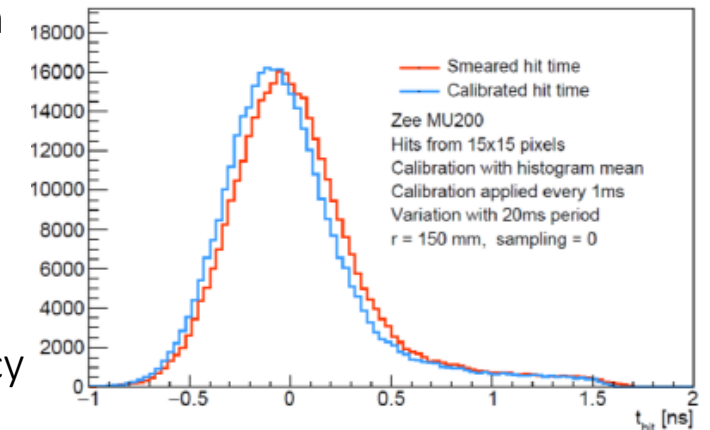
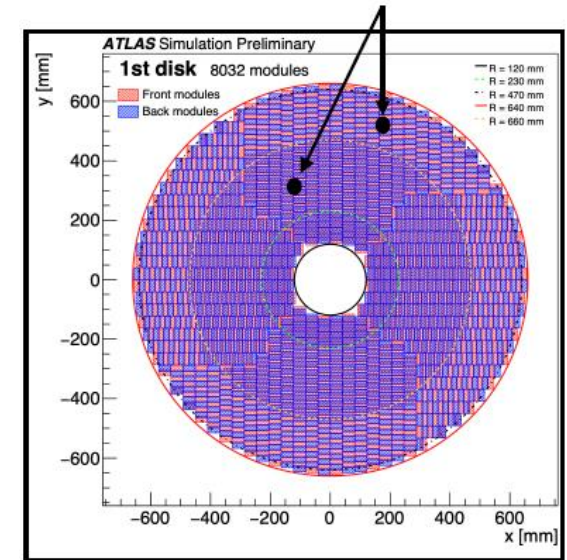
Goal: measure the same hit time for tracks from the same interaction

⇒ Need to correct various effects :

$$\text{hit time} = \text{TOA}_{t0} = t0_{\text{static_ASIC}} + t0_{\text{static_online}} + t0_{\text{dynamic_offline}}$$

- $t0$ dispersion inside one ASIC: $t0_{\text{static_ASIC}}$
 - Due to clock skew between channels, static dispersion. Offline correction using ASIC internal calibration pulser to have $t0_{\text{static_ASIC}}$ better than 5 ps
- $t0$ dispersion between ASICs: $t0_{\text{static_online}}$ and $t0_{\text{dynamic_offline}}$
 - Due to TOF (η , ϕ , flex cable length), static dispersion. Online correction using each ASIC phase shifter to adjust the TOA window and so to get $t0_{\text{static_online}}$ within ~ 100 ps.
 - Due to dynamic variations (drift of 40 MHz clock-RF, temperature ...). Offline correction using minimum bias physics events to re-adjust each ASIC $t0$ and so to have $t0_{\text{dynamic_offline}}$ within the needed accuracy of 10 ps (average of hits done over different integration windows)

Pixels



ATLAS
HGTD